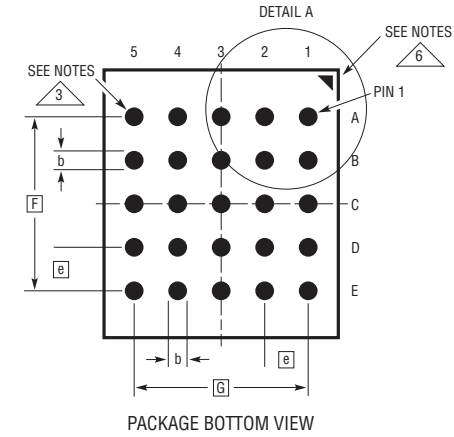
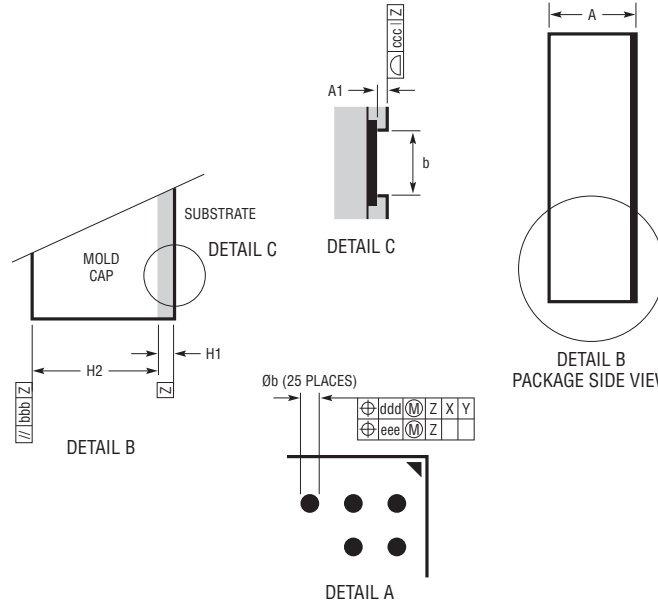
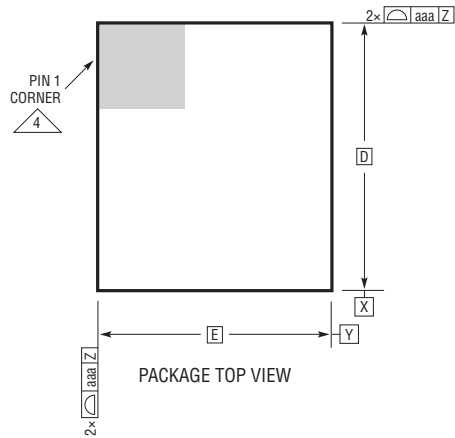
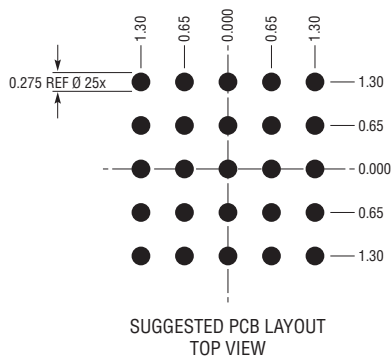


LGA Package
25-Lead (4mm × 3.5mm × 1.3mm)
(Reference LTC DWG# 05-08-1785 Rev 0)



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 LAND DESIGNATION PER JEP95
 - 4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 - 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.28	1.34	1.40	
A1	0.015	0.025	0.035	
b	0.25	0.28	0.31	PAD DIMENSION
D		4.00		
E		3.50		
e		0.65		
F		2.60		
G		2.60		
H1		0.47 REF		SUBSTRATE THK
H2		0.87 REF		MOLD CAP HT
aaa			0.10	
bbb			0.10	
ccc			0.10	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF PADS: 25

